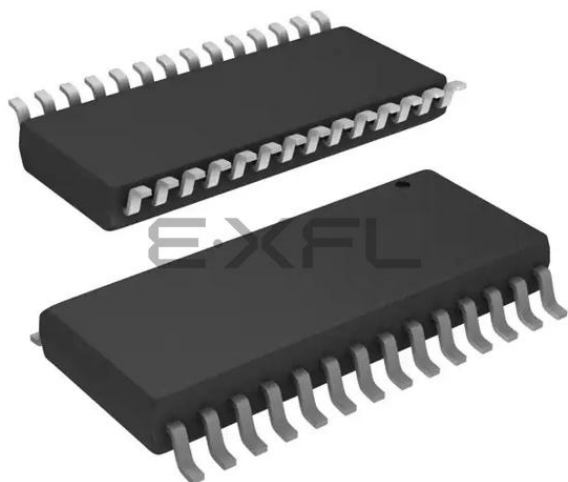




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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512gp202-h-so

FIGURE 3-2: PROGRAMMER'S MODEL

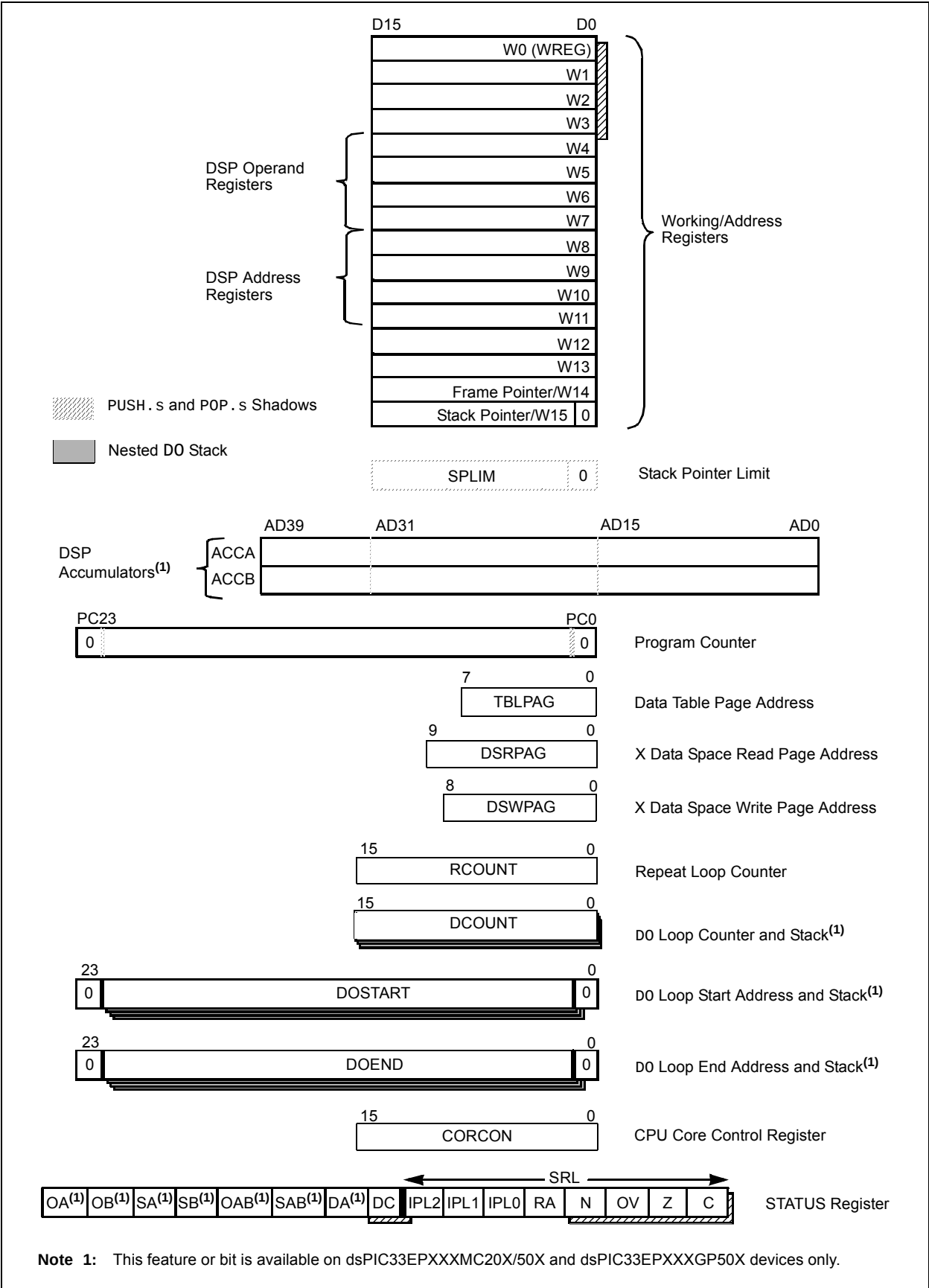


TABLE 4-4: INTERRUPT CONTROLLER REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMIF	MI2C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	—	—	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	QE11IF	PSEMIF	—	—	—	—	—	—	MI2C2IF	SI2C2IF	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	—	—	—	CRCIF	U2EIF	U1EIF	—	0000
IFS5	080A	PWM2IF	PWM1IF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS6	080C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IF	0000
IFS8	0810	JTAGIF	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS9	0812	—	—	—	—	—	—	—	—	—	PTG3IF	PTG2IF	PTG1IF	PTG0IF	PTGWDTIF	PTGSTEIF	—	0000
IEC0	0820	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	—	—	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	QE11IE	PSEMIE	—	—	—	—	—	—	MI2C2IE	SI2C2IE	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	—	—	—	—	CRCIE	U2EIE	U1EIE	0000
IEC5	082A	PWM2IE	PWM1IE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC6	082C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IE	0000
IEC8	0830	JTAGIE	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC9	0832	—	—	—	—	—	—	—	—	—	PTG3IE	PTG2IE	PTG1IE	PTG0IE	PTGWDTIE	PTGSTIEIE	—	0000
IPC0	0840	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	0842	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	0844	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	0846	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	0848	—	CNIP<2:0>			—	CMIP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC6	084C	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	084E	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	0850	—	—	—	—	—	—	—	—	—	SPI2IP<2:0>			—	SPI2EIP<2:0>			0044
IPC9	0852	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			0444
IPC12	0858	—	—	—	—	—	MI2C2IP<2:0>			—	SI2C2IP<2:0>			—	—	—	—	0440
IPC14	085C	—	—	—	—	—	QE11IP<2:0>			—	PSEMIP<2:0>			—	—	—	—	0440
IPC16	0860	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC19	0866	—	—	—	—	—	—	—	—	—	CTMUIP<2:0>			—	—	—	—	0040
IPC23	086E	—	PWM2IP<2:0>			—	PWM1IP<2:0>			—	—	—	—	—	—	—	—	4400
IPC24	0870	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IP<2:0>			4004

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-41: PMD REGISTER MAP FOR dsPIC33EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QE1MD	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD	PTGMD	—	—	—	0000
													DMA1MD					
													DMA2MD					
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-45: DMAC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
DMA0CON	0B00	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA0REQ	0B02	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA0STAL	0B04	STA<15:0>																	0000
DMA0STAH	0B06	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA0STBL	0B08	STB<15:0>																	0000
DMA0STBH	0B0A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA0PAD	0B0C	PAD<15:0>																	0000
DMA0CNT	0B0E	—	—	CNT<13:0>															0000
DMA1CON	0B10	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA1REQ	0B12	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA1STAL	0B14	STA<15:0>																	0000
DMA1STAH	0B16	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA1STBL	0B18	STB<15:0>																	0000
DMA1STBH	0B1A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA1PAD	0B1C	PAD<15:0>																	0000
DMA1CNT	0B1E	—	—	CNT<13:0>															0000
DMA2CON	0B20	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA2REQ	0B22	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA2STAL	0B24	STA<15:0>																	0000
DMA2STAH	0B26	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA2STBL	0B28	STB<15:0>																	0000
DMA2STBH	0B2A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA2PAD	0B2C	PAD<15:0>																	0000
DMA2CNT	0B2E	—	—	CNT<13:0>															0000
DMA3CON	0B30	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA3REQ	0B32	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA3STAL	0B34	STA<15:0>																	0000
DMA3STAH	0B36	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA3STBL	0B38	STB<15:0>																	0000
DMA3STBH	0B3A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA3PAD	0B3C	PAD<15:0>																	0000
DMA3CNT	0B3E	—	—	CNT<13:0>															0000
DMA3PWC	0BF0	—	—	—	—	—	—	—	—	—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0	0000	
DMA3RQC	0BF2	—	—	—	—	—	—	—	—	—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0	0000	
DMA3PPS	0BF4	—	—	—	—	—	—	—	—	—	—	—	—	PPST3	PPST2	PPST1	PPST0	0000	
DMA3LCA	0BF6	—	—	—	—	—	—	—	—	—	—	—	—	LSTCH<3:0>				000F	
DSADRL	0BF8	DSADR<15:0>																	0000
DSADRH	0BFA	—	—	—	—	—	—	—	—	DSADR<23:16>									0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.2 RTSP Operation

RTSP allows the user application to erase a single page of memory and to program two instruction words at a time. See the General Purpose and Motor Control Family tables (Table 1 and Table 2, respectively) for the page sizes of each device.

For more information on erasing and programming Flash memory, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

For erase and program times, refer to Parameters D137a and D137b (Page Erase Time), and D138a and D138b (Word Write Cycle Time) in Table 30-14 in **Section 30.0 "Electrical Characteristics"**.

Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.3.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program two adjacent words (24 bits x 2) of program Flash memory at a time on every other word address boundary (0x000002, 0x000006, 0x00000A, etc.). To do this, it is necessary to erase the page that contains the desired address of the location the user wants to change.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs.

Refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"* for details and codes examples on programming using RTSP.

5.4 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

5.4.1 KEY RESOURCES

- **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

5.5 Control Registers

Four SFRs are used to erase and write the program Flash memory: NVMCON, NVMKEY, NVMADRH and NVMADRL.

The NVMCON register (Register 5-1) enables and initiates Flash memory erase and write operations.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRH and NVMADRL. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word for programming operations or the selected page for erase operations.

The NVMADRH register is used to hold the upper 8 bits of the EA, while the NVMADRL register is used to hold the lower 16 bits of the EA.

11.7 Peripheral Pin Select Registers

REGISTER 11-1: RPIR0: PERIPHERAL PIN SELECT INPUT REGISTER 0

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INT1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **INT1R<6:0>:** Assign External Interrupt 1 (INT1) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
1111001 = Input tied to RPI121

.
.
.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 11-7: RPINR12: PERIPHERAL PIN SELECT INPUT REGISTER 12
(dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT1R<6:0>						
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **FLT2R<6:0>:** Assign PWM Fault 2 (FLT2) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **FLT1R<6:0>:** Assign PWM Fault 1 (FLT1) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 21-26: CxTRmnCON: ECANx TX/RX BUFFER mn CONTROL REGISTER
(m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI1	TXnPRI0
bit 15						bit 8	

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm ⁽¹⁾	TXLARBm ⁽¹⁾	TXERRm ⁽¹⁾	TXREQm	RTRENm	TXmPRI1	TXmPRI0
bit 7						bit 0	

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-8 See Definition for bits<7:0>, Controls Buffer n
- bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer TRBn is a transmit buffer
0 = Buffer TRBn is a receive buffer
- bit 6 **TXABTm:** Message Aborted bit⁽¹⁾
1 = Message was aborted
0 = Message completed transmission successfully
- bit 5 **TXLARBm:** Message Lost Arbitration bit⁽¹⁾
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent
- bit 4 **TXERRm:** Error Detected During Transmission bit⁽¹⁾
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent
- bit 3 **TXREQm:** Message Send Request bit
1 = Requests that a message be sent; the bit automatically clears when the message is successfully sent
0 = Clearing the bit to '0' while set requests a message abort
- bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected
- bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQ is set.

Note: The buffers, SID, EID, DLC, Data Field, and Receive Status registers are located in DMA RAM.

REGISTER 22-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **EDG1MOD:** Edge 1 Edge Sampling Mode Selection bit
 1 = Edge 1 is edge-sensitive
 0 = Edge 1 is level-sensitive
- bit 14 **EDG1POL:** Edge 1 Polarity Select bit
 1 = Edge 1 is programmed for a positive edge response
 0 = Edge 1 is programmed for a negative edge response
- bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
 1xxx = Reserved
 01xx = Reserved
 0011 = CTED1 pin
 0010 = CTED2 pin
 0001 = OC1 module
 0000 = Timer1 module
- bit 9 **EDG2STAT:** Edge 2 Status bit
 Indicates the status of Edge 2 and can be written to control the edge source.
 1 = Edge 2 has occurred
 0 = Edge 2 has not occurred
- bit 8 **EDG1STAT:** Edge 1 Status bit
 Indicates the status of Edge 1 and can be written to control the edge source.
 1 = Edge 1 has occurred
 0 = Edge 1 has not occurred
- bit 7 **EDG2MOD:** Edge 2 Edge Sampling Mode Selection bit
 1 = Edge 2 is edge-sensitive
 0 = Edge 2 is level-sensitive
- bit 6 **EDG2POL:** Edge 2 Polarity Select bit
 1 = Edge 2 is programmed for a positive edge response
 0 = Edge 2 is programmed for a negative edge response
- bit 5-2 **EDG2SEL<3:0>:** Edge 2 Source Select bits
 1111 = Reserved
 01xx = Reserved
 0100 = CMP1 module
 0011 = CTED2 pin
 0010 = CTED1 pin
 0001 = OC1 module
 0000 = IC1 module
- bit 1-0 **Unimplemented:** Read as '0'

REGISTER 23-3: AD1CON3: ADC1 CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC4 ⁽¹⁾	SAMC3 ⁽¹⁾	SAMC2 ⁽¹⁾	SAMC1 ⁽¹⁾	SAMC0 ⁽¹⁾
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS7 ⁽²⁾	ADCS6 ⁽²⁾	ADCS5 ⁽²⁾	ADCS4 ⁽²⁾	ADCS3 ⁽²⁾	ADCS2 ⁽²⁾	ADCS1 ⁽²⁾	ADCS0 ⁽²⁾
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **ADRC:** ADC1 Conversion Clock Source bit

1 = ADC internal RC clock

0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits⁽¹⁾

11111 = 31 TAD

•

•

•

00001 = 1 TAD

00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** ADC1 Conversion Clock Select bits⁽²⁾

11111111 = $T_P \cdot (ADCS<7:0> + 1) = T_P \cdot 256 = T_{AD}$

•

•

•

00000010 = $T_P \cdot (ADCS<7:0> + 1) = T_P \cdot 3 = T_{AD}$

00000001 = $T_P \cdot (ADCS<7:0> + 1) = T_P \cdot 2 = T_{AD}$

00000000 = $T_P \cdot (ADCS<7:0> + 1) = T_P \cdot 1 = T_{AD}$

Note 1: This bit is only used if SSRC<2:0> (AD1CON1<7:5>) = 111 and SSRCG (AD1CON1<4>) = 0.

2: This bit is not used if ADRC (AD1CON3<15>) = 1.

27.2 User ID Words

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 27-3.

TABLE 27-3: USER ID WORDS REGISTER MAP

File Name	Address	Bits 23-16	Bits 15-0
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

Legend: — = unimplemented, read as '1'.

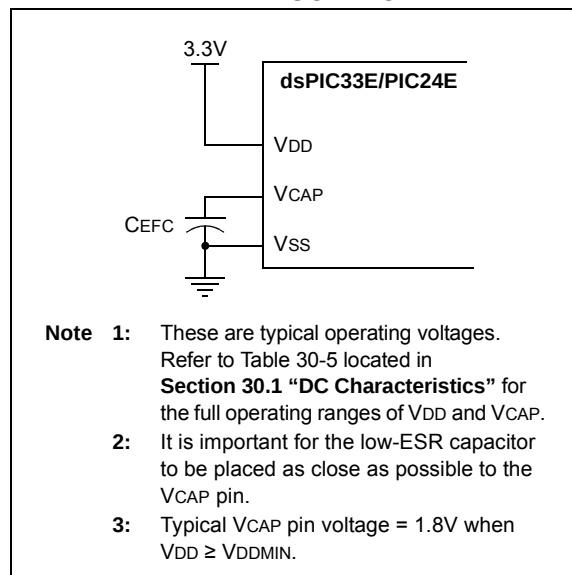
27.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 30-5 located in Section 30.0 "Electrical Characteristics".

Note: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR^(1,2,3)



27.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 30-22 of Section 30.0 "Electrical Characteristics" for specific TFSCM values.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp Range (in °C)	Maximum MIPS
			dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
—	3.0V to 3.6V ⁽¹⁾	-40°C to +85°C	70
—	3.0V to 3.6V ⁽¹⁾	-40°C to +125°C	60

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \sum I_{OH})$ I/O Pin Power Dissipation: $I/O = \sum (\{V_{DD} - V_{OH}\} \times I_{OH}) + \sum (V_{OL} \times I_{OL})$	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	$(T_J - T_A)/\theta_{JA}$			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin QFN	θ_{JA}	28.0	—	°C/W	1
Package Thermal Resistance, 64-Pin TQFP 10x10 mm	θ_{JA}	48.3	—	°C/W	1
Package Thermal Resistance, 48-Pin UQFN 6x6 mm	θ_{JA}	41	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29.0	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10 mm	θ_{JA}	49.8	—	°C/W	1
Package Thermal Resistance, 44-Pin VTLA 6x6 mm	θ_{JA}	25.2	—	°C/W	1
Package Thermal Resistance, 36-Pin VTLA 5x5 mm	θ_{JA}	28.5	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN-S	θ_{JA}	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	69.7	—	°C/W	1
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

FIGURE 30-13: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS
(dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

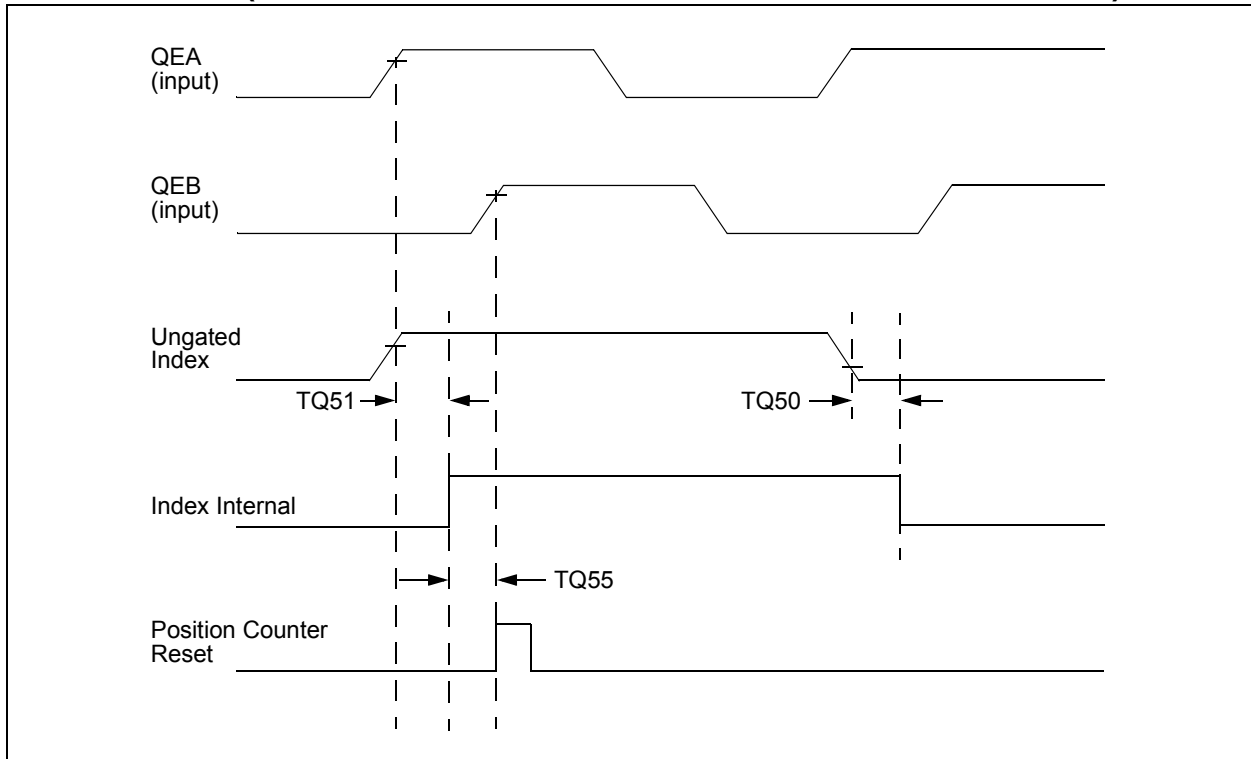


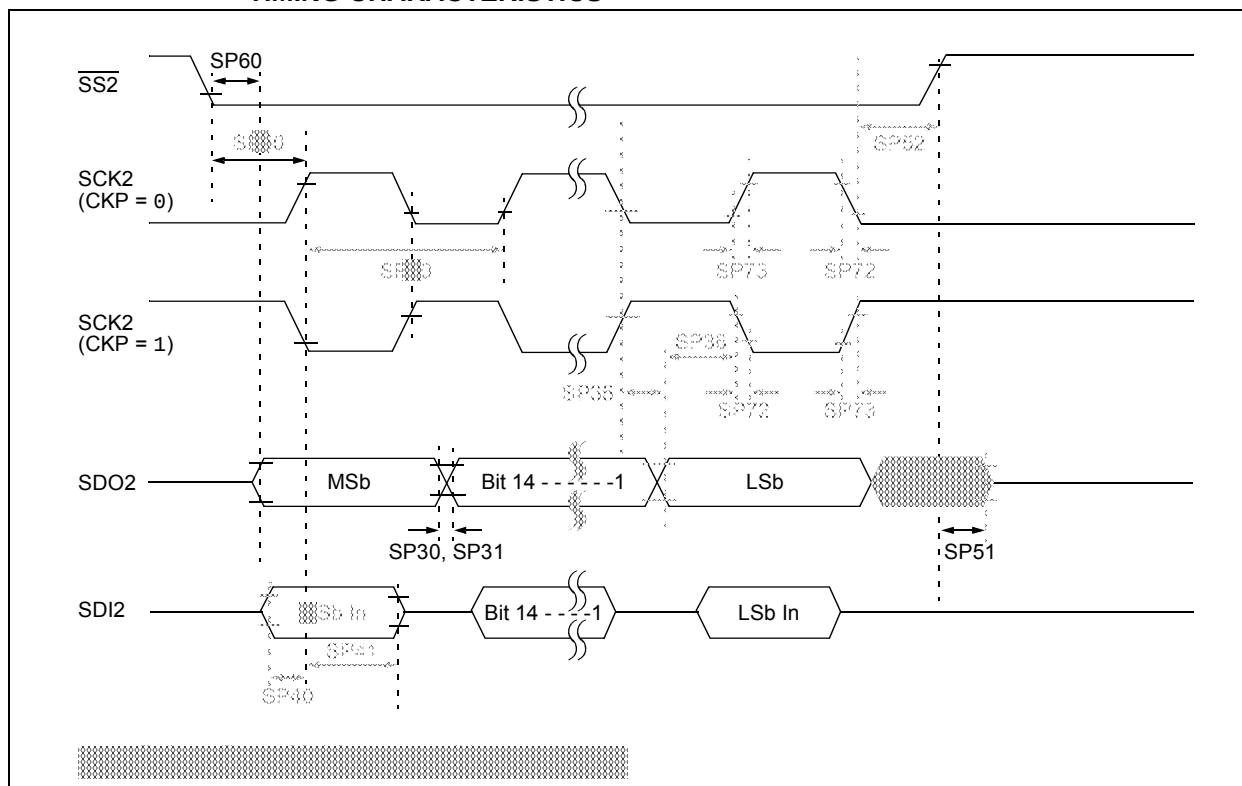
TABLE 30-32: QEI INDEX PULSE TIMING REQUIREMENTS
(dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	Symbol	Characteristic ⁽¹⁾	Min.	Max.	Units	Conditions
TQ50	TqiL	Filter Time to Recognize Low, with Digital Filter	3 * N * Tcy	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 (Note 2)
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	3 * N * Tcy	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 (Note 2)
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (ungated index)	3 Tcy	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Alignment of index pulses to QEA and QEB is shown for position counter Reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but index pulse recognition occurs on the falling edge.

**FIGURE 30-18: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)
TIMING CHARACTERISTICS**



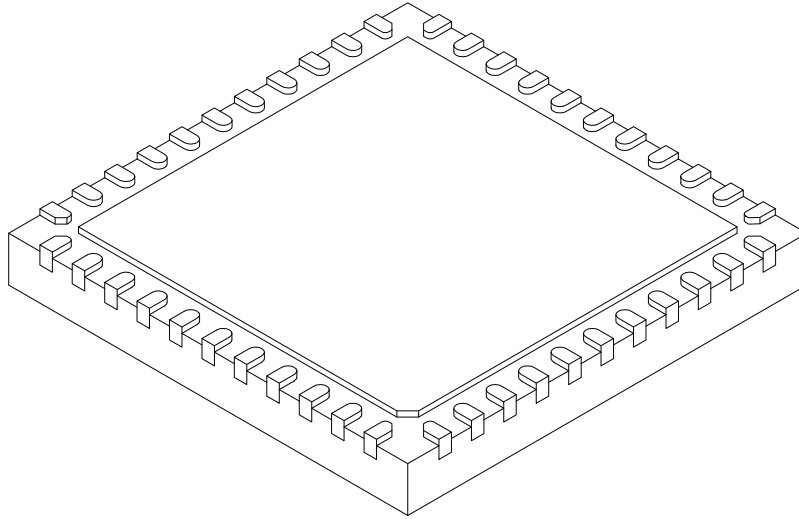
**TABLE 30-40: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	(Note 3)
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH, TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	(Note 4)

- Note 1:** These parameters are characterized, but are not tested in manufacturing.
- 2:** Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.
- 3:** The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.
- 4:** Assumes 50 pF load on all SPI2 pins.

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	44		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Width	E	8.00 BSC		
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D	8.00 BSC		
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M

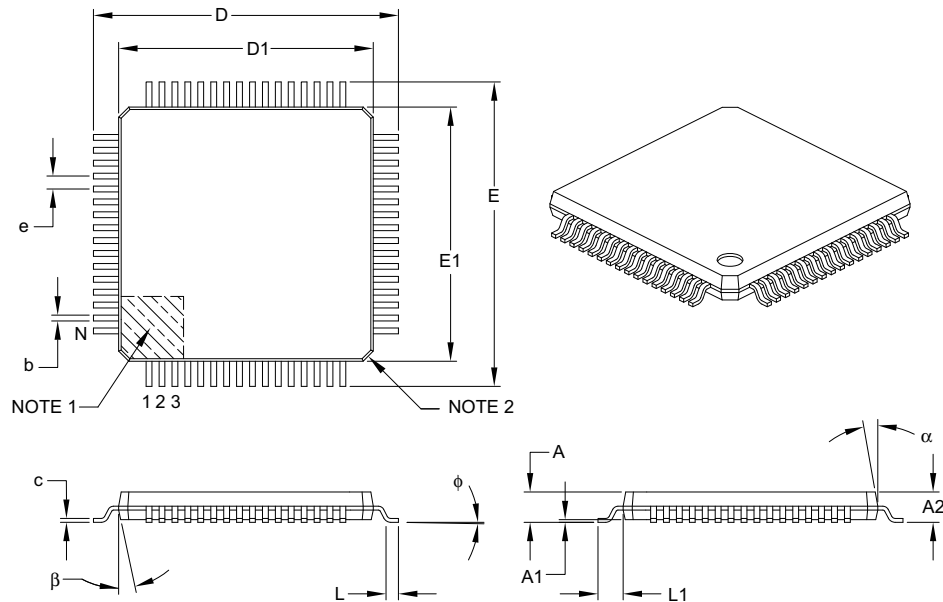
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension. usually without tolerance. for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Leads	N		64		
Lead Pitch	e		0.50 BSC		
Overall Height	A		–	–	1.20
Molded Package Thickness	A2		0.95	1.00	1.05
Standoff	A1		0.05	–	0.15
Foot Length	L		0.45	0.60	0.75
Footprint	L1		1.00 REF		
Foot Angle	ϕ		0°	3.5°	7°
Overall Width	E		12.00 BSC		
Overall Length	D		12.00 BSC		
Molded Package Width	E1		10.00 BSC		
Molded Package Length	D1		10.00 BSC		
Lead Thickness	c		0.09	–	0.20
Lead Width	b		0.17	0.22	0.27
Mold Draft Angle Top	α		11°	12°	13°
Mold Draft Angle Bottom	β		11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 “Electrical Characteristics”	Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings⁽¹⁾. Removed Parameter DC18 (V_{CORE}) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4). Updated Note 1 in the DC Characteristics: Operating Current (I_{DD}) (see Table 30-6). Updated Note 1 in the DC Characteristics: Idle Current (I_{IDLE}) (see Table 30-7). Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (I_{PD}) (see Table 30-8). Updated Note 1 in the DC Characteristics: Doze Current (I_{DOZE}) (see Table 30-9). Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12). Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated Internal FRC Accuracy Parameter F20a (see Table 30-21). Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).
Section 31.0 “Packaging Information”	Updated packages by replacing references of VLAP with TLA.
“Product Identification System”	Changed VLAP to TLA.

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 “Electrical Characteristics” (Continued)	These SPI2 Timing Requirements were updated: • Maximum value for Parameter SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-36, Table 30-37, and Table 30-38) • Maximum value for Parameter SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-40 and Table 30-42) • The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-43) These SPI1 Timing Requirements were updated: • Maximum value for Parameters SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-44, Table 30-45, and Table 30-46) • Maximum value for Parameters SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-47 through Table 30-50) • Minimum value for Parameters SP40 and SP41 see Table 30-44 through Table 30-50) Updated all Typical values for the CTMU Current Source Specifications (see Table 30-55). Updated Note1, the Maximum value for Parameter AD06, the Minimum value for AD07, and the Typical values for AD09 in the ADC Module Specifications (see Table 30-56). Added Note 1 to the ADC Module Specifications (12-bit Mode) (see Table 30-57). Added Note 1 to the ADC Module Specifications (10-bit Mode) (see Table 30-58). Updated the Minimum and Maximum values for Parameter AD21b in the 10-bit Mode ADC Module Specifications (see Table 30-58). Updated Note 2 in the ADC Conversion (12-bit Mode) Timing Requirements (see Table 30-59). Updated Note 1 in the ADC Conversion (10-bit Mode) Timing Requirements (see Table 30-60).

Revision E (April 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-4: MAJOR SECTION UPDATES

Section Name	Update Description
“16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog”	The following 512-Kbyte devices were added to the General Purpose Families table (see Table 1): • PIC24EP512GP202 • PIC24EP512GP204 • PIC24EP512GP206 • dsPIC33EP512GP502 • dsPIC33EP512GP504 • dsPIC33EP512GP506 The following 512-Kbyte devices were added to the Motor Control Families table (see Table 2): • PIC24EP512MC202 • PIC24EP512MC204 • PIC24EP512MC206 • dsPIC33EP512MC202 • dsPIC33EP512MC204 • dsPIC33EP512MC206 • dsPIC33EP512MC502 • dsPIC33EP512MC504 • dsPIC33EP512MC506 Certain Pin Diagrams were updated to include the new 512-Kbyte devices.
Section 4.0 “Memory Organization”	Added a Program Memory Map for the new 512-Kbyte devices (see Figure 4-4). Added a Data Memory Map for the new dsPIC 512-Kbyte devices (see Figure 4-11). Added a Data Memory Map for the new PIC24 512-Kbyte devices (see Figure 4-16).
Section 7.0 “Interrupt Controller”	Updated the VECNUM bits in the INTTREG register (see Register 7-7).
Section 11.0 “I/O Ports”	Added tip 6 to Section 11.5 “I/O Helpful Tips” .
Section 27.0 “Special Features”	The following modifications were made to the Configuration Byte Register Map (see Table 27-1): • Added the column Device Memory Size (Kbytes) • Removed Notes 1 through 4 • Added addresses for the new 512-Kbyte devices
Section 30.0 “Electrical Characteristics”	Updated the Minimum value for Parameter DC10 (see Table 30-4). Added Power-Down Current (I_{pd}) parameters for the new 512-Kbyte devices (see Table 30-8). Updated the Minimum value for Parameter CM34 (see Table 30-53). Updated the Minimum and Maximum values and the Conditions for parameter SY12 (see Table 30-22).